

Product Change Notification - KSRA-23UQZO342

Date: 27 Feb 2018
Product Category: 8-bit PIC Microcontrollers
Notification subject: CCB 2874 Initial Notice: Qualification of CuPdAu bond wire for selected products of 250K and 290K wafer technology available in 14L TSSOP package at MMT assembly site
Notification text: **PCN Status:**
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 250K and 290K wafer technology available in 14L TSSOP package at MMT assembly site.

Pre Change:

Assembled using gold (Au) bond wire

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (MMT)	Microchip Technology Thailand (MMT)
Wire material	Au wire	CuPdAu wire
Die attach material	2200D	2200D
Molding compound material	G600V	G600V
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MMT assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 27, 2018 (date code: 1813)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

Workweek	March 2017					-->	February 2018					March 2018				
	09	10	11	12	13		05	06	07	08	09	10	11	12	13	
Initial PCN Issue Date	X															
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date															X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
March 03, 2017: Issued initial notification.
February 27, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 27, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_KSRA-23UQZO342_Affected CPN.pdf](#)
 - [PCN_KSRA-23UQZO342_Qual Report.pdf](#)
 - [PCN_KSRA-23UQZO342_Affected CPN.xlsx](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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KSRA-23UQZ0342 -CCB 2874 Final Notice: Qualification of CuPdAu bond wire for selected products of 290K wafer technology available in 14L TSSOP package at MMT assembly site

Affected Catalog Part Number (CPN)

PCN_KSRA-23UQZ0342
CATALOG_PART_NBR
PIC16F15323-E/ST
PIC16F15323-I/ST
PIC16F15323T-E/ST
PIC16F15323T-I/ST
PIC16F15324-E/ST
PIC16F15324-I/ST
PIC16F15324T-E/ST
PIC16F15324T-I/ST
PIC16F15325-E/ST
PIC16F15325-I/ST
PIC16F15325T-I/ST
PIC16F18323-E/ST
PIC16F18323-I/ST
PIC16F18323T-E/ST
PIC16F18323T-I/ST
PIC16F18324-E/ST
PIC16F18324-I/ST
PIC16F18324T-I/ST
PIC16F18325-E/ST
PIC16F18325-I/ST
PIC16F18325T-E/ST
PIC16F18325T-I/ST
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PIC16F18326-I/ST
PIC16F18326T-E/ST
PIC16F18326T-I/ST
PIC16F18426-E/ST
PIC16F18426-I/ST
PIC16F18426T-I/ST
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PIC16LF15323-I/ST
PIC16LF15323T-I/ST
PIC16LF15324-E/ST
PIC16LF15324-I/ST
PIC16LF15324T-I/ST
PIC16LF15325-E/ST
PIC16LF15325-I/ST
PIC16LF15325T-I/ST
PIC16LF18323-E/ST
PIC16LF18323-I/ST
PIC16LF18323-I/ST024
PIC16LF18323-I/ST025
PIC16LF18323-I/STC02

KSRA-23UQZO342 -CCB 2874 Final Notice: Qualification of CuPdAu bond wire for selected products of 290K wafer technology available in 14L TSSOP package at MMT assembly site

Affected Catalog Part Number (CPN)

PCN_KSRA-23UQZO342
CATALOG_PART_NBR
PIC16LF18323T-I/ST
PIC16LF18323T-I/ST024
PIC16LF18323T-I/ST025
PIC16LF18323T-I/STC02
PIC16LF18324-E/ST
PIC16LF18324-I/ST
PIC16LF18324T-I/ST
PIC16LF18325-E/ST
PIC16LF18325-I/ST
PIC16LF18325T-I/ST
PIC16LF18326-E/ST
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PIC16LF18326T-E/ST
PIC16LF18326T-I/ST
PIC16LF18426-E/ST
PIC16LF18426-I/ST
PIC16LF18426T-I/ST